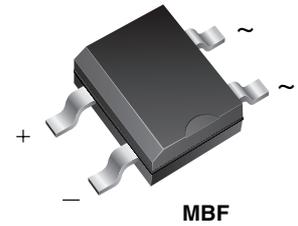
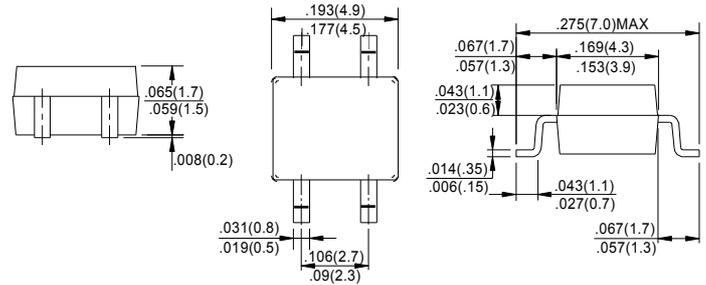


FEATURES

- UL Recognized Component
- High surge current capability
- Ideal for Printed Circuit Board
- Plastic Package - UL Flammability Classification 94V-0


MECHANICAL DATA

- Case: Transfer Molded Epoxy
- Mounting Position: Any
- Terminals: Plated leads solderable per MTL-STD-750, Method 2026



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%

Characteristic	Symbol	MB 05F	MB 1F	MB 2F	MB 4F	MB 6F	MB 8F	MB 10F	Unit
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @ $T_A=40^\circ\text{C}$	$I_{(AV)}$	0.8							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	35							A
Peak Forward Voltage at 0.8A DC	V_{FM}	1.0							V
Maximum DC Reverse Current at Rated DC Blocking Voltage @ $T_A=25^\circ\text{C}$ @ $T_A=100^\circ\text{C}$	I_{RM}	5.0 500							μA
Typical Junction Capacitance	C_J	15							pF
Typical Thermal Resistance (Note 1)	$R_{\theta JA}$	75							$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_j, T_{STG}	-55 to +150							$^\circ\text{C}$

Notes: 1. On aluminum substrate P.C.B. with an area of 0.8" x 0.8" (20 x 20mm) mounted on 0.05 x 0.05" (1.3 x 1.3mm) solder pad

Typical Characteristics

